


Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled).

2. (Currently Amended) A connection method, comprising:

electrically connecting first electrodes on a first substrate and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer, wherein the thickness of the electroconductive adhesive layer prior to connection is given by:


$$0.5 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\} \leq X \leq 2 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\}$$

where:

A^1 is ~~the~~ a height of each first electrode, B^1 is ~~the~~ an electrode width of each first electrode thereof, C^1 is ~~the~~ a width of ~~the~~ an interelectrode space for the first electrodes, A^2 is ~~the~~ a height of each second electrode, B^2 is ~~the~~ an electrode width of each second electrode thereof, C^2 is ~~the~~ a width of ~~the~~ an interelectrode space for the second electrodes (, provided that $B + C = B^1 + C^1 = B^2 + C^2$), and X is ~~the~~ a thickness of the electroconductive adhesive layer prior to connection.

3-5. (Canceled).